

Title (en)
SOLVENTLESS FORMING METHOD FOR HEAT EXCHANGER PANELS

Title (de)
LÖSUNGSMITTELFREIES HERSTELLUNGSVERFAHREN VON PLATTENWÄRMETAUSCHERN

Title (fr)
PROCEDE DE FORMAGE SANS SOLVANT POUR PANNEAUX D'ECHANGEUR THERMIQUE

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Application
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Abstract (en)
[origin: WO9855815A1] A method for forming thermoplastic heat exchanger panels without using solvents, wherein a co-extruded film is used to provide a layer of toughened, heat-sealable nylon on a layer of regular nylon, and using such panels in a gas-assisted press bonding process to form the heat exchanger panels.

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